IN THE DRAWINGS

The attached sheets of drawings replace the Figures originally filed.

Attachment: Replacement Sheets

REMARKS

In response to the Official Action mailed March 8, 2006, Applicants submit the following amendments and remarks.

The Examiner has advised that new corrected drawings must be submitted in compliance with 37 C.F.R. §1.121(d) due to informalities including poor line quality of the original drawings filed. In response to this Applicants submit new drawings in compliance with United States Patent and Trademark Office standards.

CLAIM REJECTIONS UNDER 35 U.S.C.§102 - ISAAK

26-31, 38 and 39 are rejected under Claims 1, 14, 35 U.S.C. §102(a) as being anticipated by U.S. Patent 6,426,240 to Isaak. In response to this rejection, Applicants have amended claim 1 of the present application. Claim 1 now includes the recitation that the engagement surface of the die has a length that extends at least substantially over the length of the microelectronic element such that as the substrate is being folded over the microelectronic element, the substrate is able to be folded substantially over the entire length of the microelectronic element. This is in contrast to what is taught in Isaak, which clearly shows in FIGS. 16A to 16E that the die do substantially over extend engagement surfaces not microelectronic element during the folding process. Specifically, as illustrated in FIG. 16D, the die engagement surfaces only extend about opposing end of the microelectronic element and thus would not be able to bend a substrate that must wrap around substantially all of the microelectronic element. The device of Isaak requires a secondary microelectronic element to thereby continue the folding process of the substrate if the substrate were to extend over most of the length of the

microelectronic element. Thus, Applicants assert that newly amended claim 1 as well as its dependent claims are in condition for allowance over *Isaak* and should be deemed patentable.

CLAIM REJECTIONS UNDER 35 U.S.C. §103(a)

Claims 1, 9-32, 38 and 39 are rejected under 35 U.S.C. §103(a) as being unpatentable over U.S. Patent No. 6,300,678 to Mukerji, et al., in view of Isaak. Mukerji is cited as teaching holding a substrate for accepting a microelectronic element in a first portion, the substrate having at least one portion, so that at least one folding portion of said substrate pivots with respect to said first portion about an axis between said first portion and said folding portion. As stated by the Examiner himself, Mukerji does not teach engaging a substrate with a die having an engagement surface so as to cause the folding of the substrate. Thus, the Examiner is only left with Isaak as teaching engaging the substrate with die. As already discussed, Isaak is limited to teaching die engagement surface which only extends over ends of a microelectronic element as opposed to substantially over the entire length of microelectronic element and thus it cannot cause the entire length of a substrate to be bent over substantially entire length of a microelectronic element.

Thus, Applicants assert that claim 1 as well as its dependent claims are patentably distinct from *Mujerji* in view of *Isaak* and should be deemed patentable.

As it is believed that all of the rejections set forth in the Official Action have been fully met, favorable reconsideration and allowance are earnestly solicited.

If, however, for any reason the Examiner does not believe that such action can be taken at this time, it is respectfully requested that he/she telephone applicant's

attorney at (908) 654-5000 in order to overcome any additional objections which he might have.

If there are any additional charges in connection with this requested amendment, the Examiner is authorized to charge Deposit Account No. 12-1095 therefor.

Dated: June 7, 2006

Respectfully submitted,

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